

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	145283	(heat near5 (sink spread\$3 dissipat\$3))	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 12:31
L2	75908	(substrate wafer) near100 (trench recess groove)	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 11:32
L3	186258	(substrate wafer) near100 (trench hole open\$3 recess groove)	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 12:31
L4	12798	1 and 3	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 11:33
L5	1545	4 and ((coolant (cooling near5 (liquid fluid)))	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 12:32
L7	630	5 and ((coolant (cooling near5 (liquid fluid))) same (trench hole open\$3 recess groove))	US-PGPU B; USPAT; USOCR	OR	ON	2005/10/21 11:35
L8	69509	(heat near5 (sink spread\$3 dissipat\$3))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:31
L9	167932	(substrate wafer) near100 (trench hole open\$3 recess groove)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:31
L10	258386	(substrate wafer)and (trench hole open\$3 recess groove)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:31
L11	258386	9 10	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:32
L12	3276	11 and 8	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:32

L13	85	12 and (coolant (cooling near5 (liquid fluid)))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/21 12:32
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